

## AMENDMENTS TO THE CLAIMS

*Claims 1 and 3-10 are canceled.*

1-30. (Cancelled)

31. (Previously presented) A microelectronic device comprising:  
a die, the die comprising a first side, a second side, and an edge;  
a first plate, the first plate coupled with the die, the first plate comprising a hole, the die fitting within the hole, the edge of the die being coupled with an edge of the first plate by the hole, the edge of the die being soldered with the edge of the first plate; and  
a package, the die being coupled with the package.
32. (Previously presented) The microelectronic device of claim 31, wherein the first plate exerts forces on the die to modify its effective coefficient of thermal expansion.
33. (Previously presented) The microelectronic device of claim 32, where the first plate modifies the coefficient of thermal expansion of the die to make the coefficient of thermal expansion of die more closely match the coefficient of thermal expansion of the package.
34. (Previously presented) The microelectronic device of claim 31, further comprising a second plate coupled with the package.
35. (Previously presented) The microelectronic device of claim 34, wherein the package is attached with the second plate by an adhesive.

36. (Previously presented) The microelectronic device of claim 35, wherein the first plate and second plate are constructed of the same material.
37. (Previously presented) The microelectronic device of claim 36, wherein the first plate and the second plate are constructed of copper.